

23. The surface mount light emitting diode package as recited in claim 22, wherein the line of die is adapted to form a right angle with respect to the circuit board when the package is mounted to the circuit board.

24. The surface mount light emitting diode package as recited in claim 21, wherein the plurality of light emitting diode die comprise an array of die having at least two rows and two columns.

25. The surface mount light emitting diode package as recited in claim 21, wherein the plurality of die comprise integrally connected adjacent die from a single wafer.

26. The surface mount light emitting diode package as recited in claim 25, wherein the plurality of light emitting diode die comprise a stack of at least two die arranged in a line.

27. The surface mount light emitting diode package as recited in claim 26, wherein the line of die is adapted to form a right angle with respect to the circuit board when the package is mounted to the circuit board.

28. The surface mount light emitting diode package as recited in claim 25, wherein the plurality of light emitting diode die comprise an array of die having at least two rows and two columns.--